

IN THE CLAIMS:

Please cancel claims 13-20.

Please amend the following claims:

1 1. (Amended) A laminate support used in the process of wire bonding a circuit device comprising:

2 a substrate having a first surface; and

3 a wire having a diameter positioned on said first surface of said substrate, said substrate
4 including a closed woven mesh having strands whose separation distance is equal to or
5 less than said diameter of said wire on said first surface of said substrate.
A2

1 4. (Amended) The laminate support used in the process of wire bonding a circuit device in
2 accordance with claim 1, wherein said woven mesh comprises fiberglass.

1 5. (Amended) The laminate support used in the process of wire bonding a circuit device in
2 accordance with claim 1, wherein said woven mesh is between approximately 2.5
3 and 4.0 mils thick.
A3

1 7. (Amended) A laminate support used in the process of wire bonding a circuit device comprising:

2 a substrate having a first surface; and
A4

3 a wire having a thickness positioned on said first surface of said substrate, said substrate
4 including a closed woven mesh having warp and weave strands, whose separation
5 distance is equal to or less than the thickness of said wire on said first surface of said